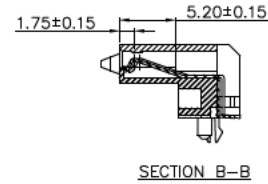
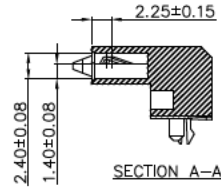
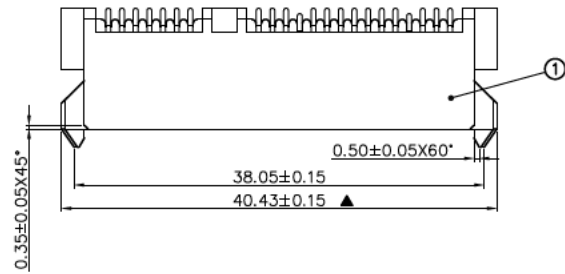
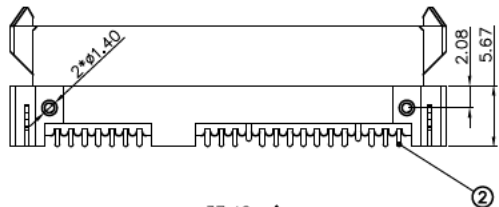
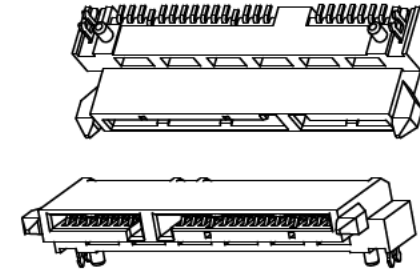
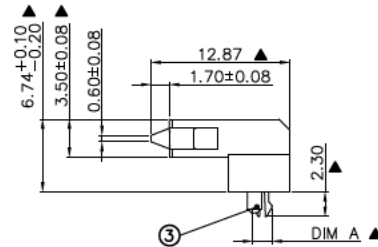
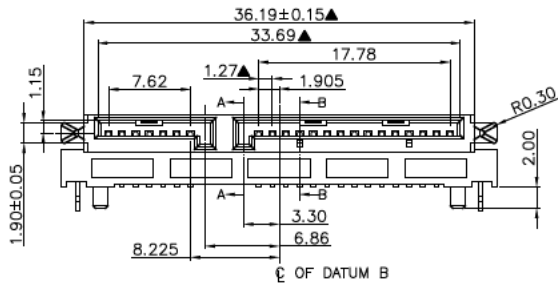


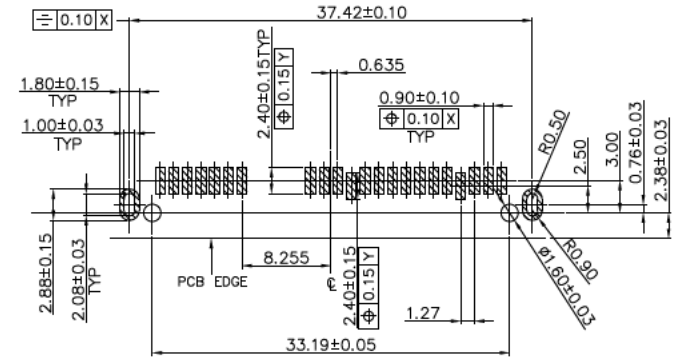
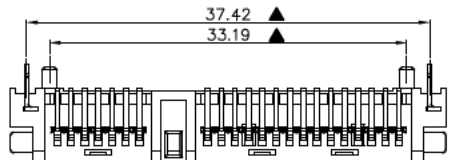
REV.	DESCRIPTION	DATE
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SPECIFICATION:  
 1.MATERIAL:  
 HOUSING: LCP 30% G/F UL 94V-0  
 COLOR:BLACK  
 CONTACT: PHOSPHOR BRONZE C5191R-H,T=0.25mm  
 PEG: BRASS C2680R-H,T=0.30mm  
 2.FINISH:  
 CONTACT:1u" GOLD/TIN PLATING ON CONTACT AREA  
 100u" MIN. TIN PLATING ON SOLDER TAILS  
 50u" MIN.NICKEL UNDERPLATING OVER ALL  
 PEG:100u" MIN. TIN PLATING ON SOLDER TAILS  
 50u" MIN.NICKEL UNDERPLATING OVER ALL



ITEM	DIM A
1	2.10
2	2.30
3	2.45
4	2.59



RECOMMEND PCB LAYOUT (T=1.2)  
 PCB TOLERANCE:±0.05

					GENERAL TOLERANCE		Rev.	A		
3	Board lock	Brass C2680		Tin/Ni Plated	.X±0.30	.X°±3°				
2	Terminal	Pho.Bronze C5191R-H		Gold/Tin Plated	.XX±0.20	.XX°±2°				Drawn No.
1	Housing	High Temp	Black	UL 94V-0	.XXX±0.05	.XXX°±0.5°	Drawn Daniel	Date 2017/07	SM C07 1120 35	
	NO.	DESCRIPTION	MATERIAL	COLOR	REMARK	SCALE	UNIT	Check		Date
						1:1	mm	Approve Daniel		Date 2017/07

SATA 7+15 P SMT  
 H: 6.74mm